

***IN THE UNITED STATES PATENT AND TRADEMARK OFFICE***

Applicants: Lopatin, *et al.*  
Title: METHOD OF USING TERNARY COPPER  
ALLOY TO OBTAIN A LOW RESISTANCE  
AND LARGE GRAIN SIZE INTERCONNECT  
Appl. No.: 09/994,395  
Filing Date: 11/26/2001  
Examiner: Ori Nadav  
Art Unit: 2811  
Confirmation Number: 7882

REPLY UNDER 37 CFR 1.116

Mail Stop Amendment  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

This communication is responsive to the Final Office Action dated July 12, 2007, concerning the above-referenced patent application.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this document.

**Remarks/Arguments** begin on page 6 of this document.